

OCT 17 2005

Reply Under 37 CFR 1.116
Expedited Procedure
Art Unit 2825

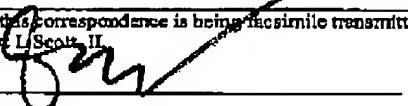
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: HAMASAKI
 Serial No.: 10/814,180
 Filed: 4/1/2004
 Title: METHOD OF RESIN-SEALING A SEMICONDUCTOR DEVICE, AND FORMING DIE FOR RESIN SEALING THE SEMICONDUCTOR DEVICE

Atty. Dkt.: 01-615
 Art Unit: 2825
 Examiner: MALSAWMA

Mail Stop AF
 Commissioner for Patents
 P.O. Box 1450
 Alexandria, VA 22313-1450

Date: October 17, 2005

CERTIFICATE OF FACSIMILE TRANSMISSION	
I hereby certify that this correspondence is being facsimile transmitted to the USPTO (Fax. No. 571-273-8300) on this date: 17 October 2005	
Typed Name: Robert L Scott, II	
Signature: 	
Signature: _____	

AMENDMENT UNDER 37 CFR 1.116

Sir:

In response to the office action mailed May 16, 2005, the time for response to which, since falling on Sunday, October 16, 2005, is automatically extended to today, Monday, October 17, 2005, please amend the application as follows:

Amendments to the Claims are reflected in the listing of claims that begins on page 2 of this paper.

Remarks begin on page 3 of this paper.